

B3  
(Contd)

can be used to grade the severity of the defect. The production and use of thermal asperity detection heads with the thermal transducer placed on the air bearing surface are described further in commonly assigned and simultaneously filed U.S. Patent application, 09/178,580 to Sundaram et al., entitled "GLIDE HEAD FOR ASPERITY DETECTION," incorporated herein by reference.

IN THE CLAIMS

✓  
Please amend claims 11-13 and 15-20 as follows:

Sub  
C1  
B1

11. (Twice Amended) A wafer including a glide head array including a plurality of rows and a plurality of columns of glide portions having air bearing surfaces contoured on a surface of the wafer and an array of glide transducers on the wafer to form a plurality of glide heads.

B5  
Sub  
C1

12. (Amended) The wafer of claim 11 wherein the array of air bearing surfaces comprise rails.

13. (Amended) The wafer of claim 11 wherein said contoured surface of the wafer has a flatness less than about 3  $\mu\text{m}$ .

Sub  
C1  
B1

15. (Amended) The wafer of claim 11 wherein the contoured surface of the wafer has a peak-to-valley flatness less than about 1  $\mu\text{inch}$ .

B6  
C1

16. (Amended) The wafer of claim 11 wherein the contoured surface of the wafer has a surface flatness less than about 1  $\mu\text{inch}$ .

17. (Amended) The wafer of claim 11 wherein the array of glide transducers are mounted on a wafer surface opposite to the contoured surface of the wafer.

18. (Amended) The wafer of claim 11 wherein the contoured surface

Sub C3  
P6  
(cont'd)

of the wafer has a flatness less than about 0.5  $\mu$ inch.

19. (Amended) A glide head formed from the glide head array of the wafer of claim 11.

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20. (Amended) A detection system for detecting asperities including the glide head of claim 19 supported on an armature operable to position the glide head over a disc surface for glide testing and including a transducer on the glide head to detect interactions between the glide head and the disc surface.

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✓  
Please add new claims 21-25 as follows:

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21. (New) The wafer of claim 11 where the array of glide transducers includes an array of piezoelectric transducers.

B1  
22. (New) The wafer of claim 11 wherein the glide head array includes an array of wing portions and the array of glide transducers are formed thereon.

Sub C4  
23. (New) The wafer of claim 11 wherein the array of glide transducers are formed on the contoured surface of the wafer.

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24. (New) The wafer of claim 23 wherein the array of glide transducers includes an array of thermal transducers.

Sub C5  
25. (New) The wafer of claim 24 wherein the thermal transducer are formed of a magnetoresistive sensor. ) 11/2/21

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